

L Number	Hits	Search Text	DB	Time stamp
1	1571	@py>=2001 and (underfill\$3 stress) same (chip\$1 die dice\$1) same (tack\$2 adhe\$5 glue\$1 resin\$4) same (bump\$1 pad\$1 electrode\$1 lead\$1)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:11
2	239	(@py>=2001 and (underfill\$3 stress) same (chip\$1 die dice\$1) same (tack\$2 adhe\$5 glue\$1 resin\$4) same (bump\$1 pad\$1 electrode\$1 lead\$1)) and packag\$3 and underfill\$3 same (chip\$1 die dice\$1) same (tack\$2 adhe\$5 glue\$1 resin\$4) near10 (bump\$1 pad\$1 electrode\$1 lead\$1)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:13
3	137	((@py>=2001 and (underfill\$3 stress) same (chip\$1 die dice\$1) same (tack\$2 adhe\$5 glue\$1 resin\$4) same (bump\$1 pad\$1 electrode\$1 lead\$1)) and packag\$3 and underfill\$3 same (chip\$1 die dice\$1) same (tack\$2 adhe\$5 glue\$1 resin\$4) near10 (bump\$1 pad\$1 electrode\$1 lead\$1)) and underfill\$3 same (tack\$2 adhe\$5 glue\$1 resin\$4) near10 (bump\$1 pad\$1 electrode\$1 lead\$1) same (cur\$3 bak\$3 heat\$3 thermal\$2)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:15